



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D <i>* : Required Field</i>

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	21-08-2017
<b>Company Unique ID</b>	NL 008751171801		
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Contact Phone *</b>	Refer to Supplier Comment section	<b>Contact Email *</b>	Refer to Supplier Comment section
<b>Authorized Representative *</b>	MDG MD CHAMPION	<b>Representative Title</b>	MDG MD CHAMPION
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32F100ZCT6B	P21A*428XXXA	A	9998	21-08-2017
	Amount	UoM	Unit type	ST ECOPACK Grade
	1315,00	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable; if coating is used or other bulk termination	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	20x20x1.4	144	L bend	
Comment	Package : 1A LQFP 144 20X20X1.4 2 0099183			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-7th July 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	P21A*428XXXA				6000000.0	0.0
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	11,438	mg	supplier	die	Silicon (Si)	7440-21-3		10,724	mg	937576	8155
				supplier	metallization	Aluminium (Al)	7429-90-5		0,041	mg	3585	31
				supplier	metallization	Copper (Cu)	7440-50-8		0,204	mg	17835	155
				supplier	metallization	Cobalt (Co)	7440-48-4		0,038	mg	3322	29
				supplier	metallization	Titanium (Ti)	7440-32-6		0,011	mg	962	8
				supplier	metallization	Tungsten (W)	7440-33-7		0,022	mg	1923	17
				supplier	Passivation	Silicon Nitride	12033-89-5		0,027	mg	2361	21
				supplier	Passivation	Silicon Oxide	7631-86-9		0,258	mg	22556	196
				supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0,113	mg	9879	86
				LEADFRAME (MHT- C194 PFF)	M-011 Other inorganic materials	256,512	mg	supplier	ALLOY	Copper (Cu)	7440-50-8	
supplier	ALLOY	Iron (Fe)	7439-89-6						5,932	mg	23126	4511
supplier	ALLOY	Zinc (Zn)	7440-66-6						0,297	mg	1158	226
supplier	ALLOY	Phosphorus (P)	7723-14-0						0,074	mg	288	56
supplier	COATING	Nickel (Ni)	7440-02-0						9,042	mg	35250	6876
supplier	COATING	Palladium (Pd)	7440-05-3						0,192	mg	749	146
supplier	COATING	Gold (Au)	7440-57-5						0,093	mg	363	71
supplier	GLUE	Epoxy resin A	9003-36-5						0,100	mg	50176	76
supplier	GLUE	Epoxy resin B	Proprietary						0,149	mg	74762	113
supplier	GLUE	Silver(Ag)	7440-22-4						1,395	mg	699950	1061
DIE ATTACH (CRM - 1076YB)	M-011 Other inorganic materials	1,993	mg	supplier	GLUE	Silica	Proprietary		0,299	mg	150025	227
				supplier	GLUE	Hardener	Proprietary		0,050	mg	25088	38
				supplier	BONDING WIRE	Gold (Au)	7440-57-5		2,493	mg	990071	1896
				supplier	BONDING WIRE	Palladium (Pd)	7440-05-3		0,025	mg	9929	19
				supplier	MOLDING COMPOUND	Epoxy Resin	Proprietary		104,035	mg	101288	79114
				supplier	MOLDING COMPOUND	Silica fused (SiO3)	60676-86-0		874,994	mg	837939	-334605
				supplier	MOLDING COMPOUND	Phenol Resin	Proprietary		57,219	mg	55708	43513
				supplier	MOLDING COMPOUND	Carbon Black	1333-86-4		5,202	mg	5065	3956
				supplier	CONNECTION COATING	Nickel (Ni)	7440-02-0		1,061	mg	974288	807
				supplier	CONNECTION COATING	Palladium (Pd)	7440-05-3		0,023	mg	21120	17
supplier	CONNECTION COATING	Gold (Au)	7440-57-5		0,005	mg	4591	4				